

Sheet 1 of 1

Form PTO-1449	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DKT. NO.	SERIAL NO.
		219.40779X00	

INFORMATION DISCLOSURE STATEMENT  
BY APPLICANT

(Use several sheets if necessary)

APPLICANT  
B. CHANDRAN ET AL.FILING DATE  
December 21, 2001GROUP  
2827

## U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date
AV	5,369,551	11/29/94	Gore et al.			11/08/93
	5,872,401	02/16/99	Huff et al.			02/29/96
	5,889,652	03/30/99	Turturro			04/21/97
	5,931,371	08/03/99	Pao et al.			01/16/97
AV	5,936,304	08/10/99	Lü et al.			12/10/97
AV	6,049,124	04/11/00	Raiser et al.			12/10/97
AG						
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## FOREIGN PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation/ Abstract	
						Yes	No
AM							
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## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

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Examiner	John B. Vizcarra	Date Considered
		June 28, 2003

10/02/2019  
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10/02/2019

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(Use several sheets if necessary)

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B. CHANDRAN ET AL.

FILING DATE

December 21, 2001

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## U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date
BR	5,369,551	11/29/94	Gore et al.	361	767	11/08/93
	5,872,401	02/16/99	Huff et al.	257	750	02/29/96
AC	5,889,652	03/30/99	Turturro	361	719	04/21/97
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AE	5,936,304	08/10/99	Lii et al.	257	778	12/10/97
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AM							
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## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

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Examiner

John B. Virginis

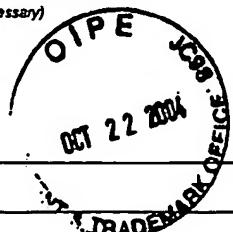
Date Considered

April 29, 2003

Paper No. 0403a

10/02/2019  
12/21/01

Substitute for form 1449A/PTO

INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT  
(Use as many sheets as necessary)

Complete if Known	
Application Number	10/023,819
Filing Date	December 21, 2001
First Named Inventor	Chandran, Biju
Group Art Unit	2827 2841
Examiner Name	Vigushin, John
Sheet 1 of 1	
Attorney Docket No: 884.A27US1	

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<i>JBV</i>	US-6,402,012	06/11/2002	Bolduc, T. D.	228	180.22	11/08/1999
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## FOREIGN PATENT DOCUMENTS

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T <sup>2</sup>

## OTHER DOCUMENTS – NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>2</sup>
<i>JBV</i>		HONG, B. Z., "Thermal Fatigue Analysis of CBGA Package with Lead-Free Solder Fillets", <u>Proceedings of the 1998 Intersociety Conference on Thermal Phenomena</u> , (Aug., 1998),205-211	
<i>JBV</i>		KARIM, Z. S., et al., "Lead-Free Bump Interconnections for Flip-Chip Applications", <u>Proceedings of the 2000 IEEE/CPMT International Electronics Manufacturing Technology Symposium</u> , (Jan., 2000),274-278	
<i>JBV</i>		WANG, T., et al., "Studies on A Novel Flip-Chip Interconnect Structure-Pillar Bump", <u>Proceedings of the 2001 Electronic Components and Technology Conference</u> , (Apr., 2001),5 p.	
<i>JBV</i>		XIAO, G., et al., "The Effect of Cu Stud Structure and Eutectic Solder Electroplating on Intermetallic Growth and Reliability of Flip-Chip Solder Bump", <u>Proceedings of the 2000 Electronic Components and Technology Conference</u> , (Sep., 2000),54-59	

*Page No. 1004*

EXAMINER

DATE CONSIDERED

*April 08, 2005*

Substitute Disclosure Statement Form (PTO-1449)

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. 1 Applicant's unique citation designation number (optional) 2 Applicant is to place a check mark here if English language Translation is attached